Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) A method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component comprising a kneading step of kneading a conductive powder, a binder and a solvent to form a clay-like mixture and a slurrying step of adding the same solvent as that used at the kneading step to the mixture obtained by the kneading step to lower the viscosity of the mixture, thereby slurrying the mixture.

2. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~Claim~~ claim 1, wherein the conductive powder, the binder and the solvent are kneaded until the mixture reaches the wetting point (ball point) thereof.

3. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~Claim~~ claim 1 ~~or 2~~, wherein the conductive powder, the binder and the solvent are kneaded until the solids concentration of the mixture reaches 84 to 94%.

4. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~any one of Claim 1 to 3~~ claim 1, wherein the dielectric powder, the conductive powder, the binder and the solvent are kneaded using a mixer selected from a

group consisting of a high speed shearing mixer, a planetary type kneading machine and a kneader.

5. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~Claim~~ claim 3 ~~or 4~~, which comprises steps of adding 0.25 to 1.7 weight parts of the binder and 3.0 to 15.0 weight parts of the solvent to 100 weight parts of the conductive powder and kneading the conductive powder, the binder and the solvent until the solids concentration of the mixture reaches 84 to 94%.

6. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~Claim~~ claim 5, which comprises steps of adding 0.5 to 1.0 weight parts of the binder and 2.0 to 10.0 weight parts of the solvent to 100 weight parts of the conductive powder and kneading the conductive powder, the binder and the solvent until the solids concentration of the mixture reaches 85 to 92%.

7. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~any one of Claim 1 to 6~~ claim 1, which comprises steps of dissolving the binder into the solvent, thereby preparing an organic vehicle, adding 3 to 15 weight % of the organic vehicle to the conductive powder and kneading the conductive powder, the binder and the solvent.

8. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~any one of Claim 1 to 7~~ claim 1, which comprises a step of adding a

dispersing agent to the mixture obtained by the kneading step, thereby slurrying the mixture.

9. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~Claim~~ claim 8, which comprises steps of adding 0.25 to 2.0 weight parts of the dispersing agent with respect to 100 weight parts of the conductive powder to the mixture obtained by the kneading step, thereby lowering the viscosity of the mixture, and then adding the solvent to the mixture, thereby slurrying the mixture.

10. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~any one of Claim 1 to 7~~ claim 1, which further comprises a step of continuously dispersing the slurry obtained by the slurrying step using a closed type emulsifier.

11. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~Claim~~ claim 10, wherein the slurry obtained by the slurrying step is continuously dispersed using a homogenizer.

12. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~Claim~~ claim 10, wherein the slurry obtained by the slurrying step is continuously dispersed using a colloid mill.

13. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~any one of Claim 1 to 12~~ claim 1, wherein a binder selected from a group consisting of ethylcellulose, polyvinyl butyral, acrylic resin and mixtures thereof is employed as the binder.

14. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~any one of Claim 1 to 13~~ claim 1, wherein a solvent selected from a group consisting of terpineol, dihydroterpineol, butyl carbitol, butyl carbitol acetate, terpineol acetate, dihydroterpineol acetate, kerosene and mixtures thereof is employed as the solvent.

15. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~any one of Claim 1 to 14~~ claim 1, wherein a nonionic dispersing agent is employed as the dispersing agent.

16. (Currently Amended) ~~A~~ The method for preparing a conductive paste for an inner electrode of a multi-layered ceramic electronic component in accordance with ~~Claim~~ claim 15, wherein a polyethyleneglycol system dispersing agent whose hydrophile-liophile balance (HLB) is 5 to 7 is employed as the dispersing agent.